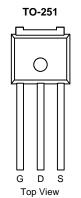
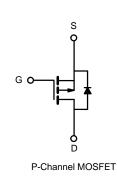


# P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A) <sup>d</sup>	Q <sub>g</sub> (Typ.)		
- 30	0.018 at V <sub>GS</sub> = - 10 V	- 40	13 nC		
- 30	0.022 at V <sub>GS</sub> = - 4.5 V	- 35	13110		





#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> Tested

### Pb-free RoHS

ROHS COMPLIANT HALOGEN FREE

#### **APPLICATIONS**

- Load Switch
- · Battery Switch

ABSOLUTE MAXIMUM RATINGS $T_A =$	= 25 °C, unless other	erwise noted		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	- 30	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20	v
	T <sub>C</sub> = 25 °C		- 40	
Continuous Drain Current (T <sub>.I</sub> = 150 °C)	T <sub>C</sub> = 70 °C	1 . [	- 35	
Continuous Diam Current (1) = 130°C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	- 30.0 <sup>a, b</sup>	
	T <sub>A</sub> = 70 °C		- 28 <sup>a, b</sup>	A
Pulsed Drain Current	I <sub>DM</sub>	- 150		
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	I-	- 3.5	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	ls –	- 2.1 <sup>a, b</sup>	
	T <sub>C</sub> = 25 °C		40	
Maximum Dawar Dissination	T <sub>C</sub> = 70 °C	P <sub>D</sub>	32	W
Maximum Power Dissipation	T <sub>A</sub> = 25 °C		2.5 <sup>a, b</sup>	VV
	T <sub>A</sub> = 70 °C	1 -	1.6 <sup>a, b</sup>	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>a, c</sup>	t ≤ 10 s	R <sub>thJA</sub>	40	50	°C/W	
Maximum Junction-to-Foot	Steady State	R <sub>thJF</sub>	24	30	1 10/00	

#### Notes

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 95 °C/W.
- d. Based on  $T_C = 25$  °C.



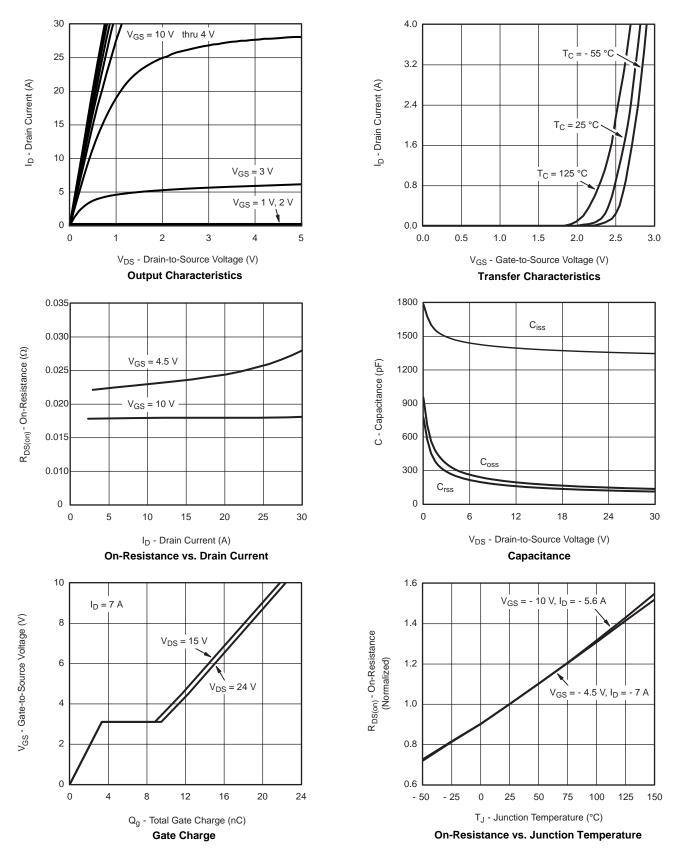
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						<u> </u>
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V, } I_{D} = -250  \mu\text{A}$	- 30			V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	In = - 250 µA		- 31		mV/°C
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_{J}$			4.5		
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0		- 2.5	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
7 0 1 1/1 5 1 0 1	1	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$		-1		μA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 5	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$	- 20			Α
	D	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 7.0 A		0.018		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 5.6 A		0.022		Ω
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 7.0 A		18		S
Dynamic <sup>b</sup>						
Input Capacitance	C <sub>iss</sub>			1455		pF
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		180		
Reverse Transfer Capacitance	C <sub>rss</sub>			145		
T. 10 . 0	$Q_g$	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -7.0 \text{ A}$		25	38	
Total Gate Charge				13	20	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -7.0 \text{ A}$		3.5		nC
Gate-Drain Charge	Q <sub>gd</sub>			5.5		
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.4	2.0	4.0	Ω
Turn-On Delay Time	t <sub>d(on)</sub>			10	20	
Rise Time	t <sub>r</sub>	$V_{DD} = -15 \text{ V}, R_{L} = 2.7 \Omega$		13	20	
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_{D} \cong -5.6 \text{ A}, V_{GEN} = -10 \text{ V}, R_{g} = 1 \Omega$		23	35	
Fall Time	t <sub>f</sub>			9	18	
Turn-On Delay Time	t <sub>d(on)</sub>			38	57	ns
Rise Time	t <sub>r</sub>	$V_{DD} = -15 \text{ V}, R_{L} = 2.7 \Omega$		89	134	1
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong -5.6 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		22	33	1
Fall Time	t <sub>f</sub>			11	17	1
Drain-Source Body Diode Characteris	stics					
Continous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 6.5	Α
Pulse Diode Forward Current	I <sub>SM</sub>				- 30	^
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = - 5.6 A, V <sub>GS</sub> = 0 V		- 0.71	- 1.2	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>			22	33	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	L _ F.G.A. dl/dt _ 100 A/··o T		17	26	nC
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = -5.6 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		13		ns
Reverse Recovery Rise Time	t <sub>b</sub>			9		

#### Notes:

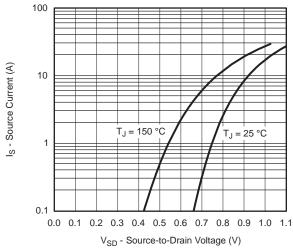
- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

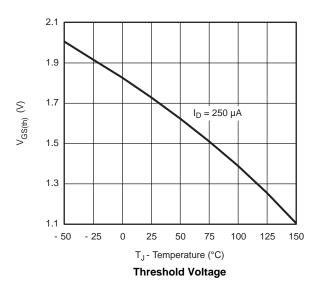








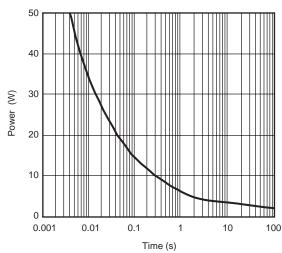
#### Source-Drain Diode Forward Voltage



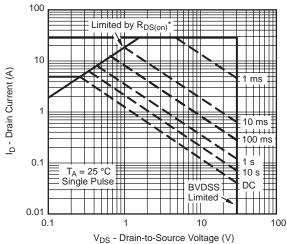
 $C_{\text{O}} = 7 \text{ A}$   $C_{\text{O}$ 

V<sub>GS</sub> - Gate-to-Source Voltage (V)

On-Resistance vs. Gate-to-Source Voltage



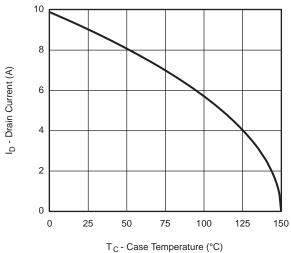
Single Pulse Power, Junction-to-Ambient



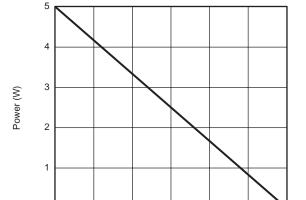
\* V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified

Safe Operating Area





Current Derating\*



0

0

25

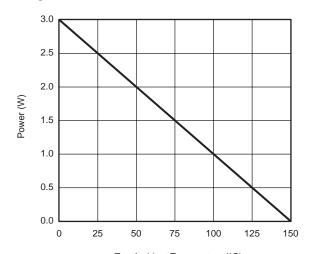
50



75

100

125

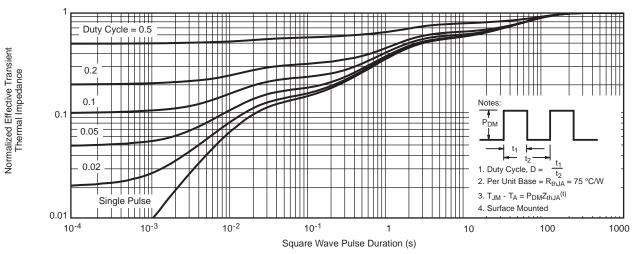


 $\label{eq:TA} T_A \text{ - Ambient Temperature (°C)}$  Power Derating, Junction-to-Ambient

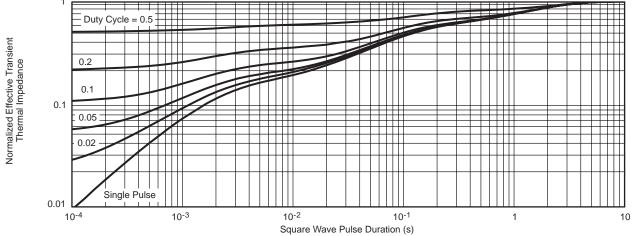
150

<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





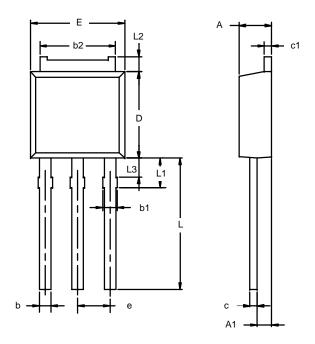
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



### TO-251AA (DPAK)



Note:	Dimension	L3 is fo	r reference	only.
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	MILLIMETERS		INC	HES	
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
с1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
E	6.48	6.73	0.255	0.265	
е	2.28 BSC		0.090 BSC		
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	
ECN: S-03946—Rev. E, 09-Jul-01 DWG: 5346					

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